SK 55 DGL 126



SEMITOP[®] 3

3-phase bridge rectifier + brake chopper

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Target Data

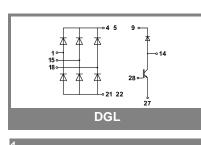
Features

- Compact design
- · One screw mounting
- Heat transfer and isolation through direct copper bonded alumium oxide ceramic (DCB)
- Trench IGBT technology
- CAL Technology FWD

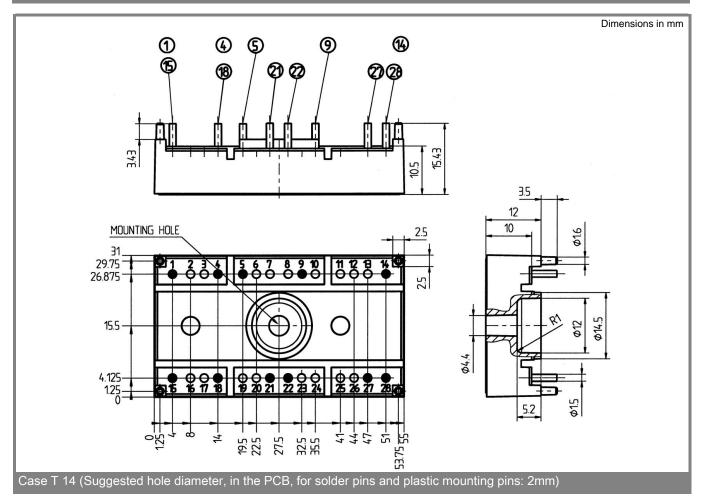
Typical Applications

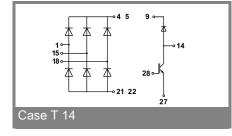
Rectifier

Absolute	Maximum Ratings	T _s = 25°C, un	less of	therwise sp	ecified
Symbol Conditions		Values		Unit	
IGBT - Ch		-			•••••
V _{CES}		1	1200		V
I _C	T _s = 25 (80) °C		0 (32)		Å
с І _{СМ}	$T_s = 25 (80) °C$, tp $\le 1 ms$		0 (64)		A
V _{GES}			±20		V
		40	+150	1	°C
T _j		-40	+150		U
Diode - Cł		1	E (2E)		
	$T_s = 25 (80) °C$		5 (35)		A
I _{FM} = -I _{CM} т	$T_s = 25 (80) \ ^\circ C, tp \le 1 \ ms$	90 (70) -40 +150			A
Т _ј		-40	+150		°C
Rectifier	I	1	1000		
V _{RRM}	T - 00 °C		1600		V
I _{FAV} / I _{TAV}	$T_s = 80 °C$	20 370			A
I _{FSM} / I _{TSM}	$t_p = 10 \text{ ms}$, sin 180 °, $T_j = 25 \text{ °C}$				A A²s
l ² t	t _p = 10 ms , sin 180 ° ,T _j = 25 °C	685			-
Т _ј		-40 +150			°C
T _{sol}	Terminals, 10s		260		°C
T _{stg}		-40	+125	i	°C
V _{isol}	AC, 1 min. / 1s	250	0 / 3000)	V
-		T 05%0			
Character		T _s = 25°C, un	less of	therwise sp	
-	Conditions	min.	typ.	max.	Units
IGBT - Ch					
V _{CEsat}	I _C = 35 A, T _j = 25 (125) °C	1	,7 (2)	2,1	V
V _{GE(th)}	$V_{GE} = V_{CE}, I_C = 1,5 \text{ mA}$	5	5,8	6,5	V
V _{CE(TO)}	T _j = 25 °C (125) °C		(0,9)	1,2	V
Т	T _j = 25 °C (125) °C	2	0 (31)	26	mΩ
C _{ies}	V _{CE} = 25 V _{GE} = 0 V, f = 1 MHz		2,4		nF
C _{oes}	V _{CE} = 25 V _{GE} = 0 V, f = 1 MHz		0,5		nF
C _{res}	V _{CE} = 25 V _{GE} = 0 V, f = 1 MHz		0,4		nF
R _{th(j-s)}	per IGBT			1,05	K/W
t d(on)	under following conditions		85		ns
t _r `´	V _{CC} = 300 V, V _{GE} = ± 15 V		30		ns
t _{d(off)}	I _C = 30 A, T _i = 125 °C		430		ns
t _f `´	$R_{Gon} = R_{Goff} = 22 \Omega$		90		ns
E _{on}	inductive load		4,6		mJ
E _{off}			4,3		mJ
Diode - Ch	nopper				•
V _F = V _{EC}	I _F = 45 A, T _j = 25 (125) °C		5 (1,5)	1,77 (1,77)	V
V _(TO)	T _j = °C (125) °C	e e	0,92)		V
ſΤ	T _j = °C (125) °C	(13,4)		mΩ
R _{th(j-s)}	per diode			1,2	K/W
RRM	under following conditions		30		Α
Q _{rr}	I _F = 50 A, V _R = 600 V		10		μC
E	V _{GE} = 0 V, T _i = 125 °C				mJ
	di _{F/dt} = 500 A/µs				
					1
Diode rect		1		1,25	V
Diode rect	I _F = 25 A, T _j = 25 °C T _i = 150 °C		0,8		V
V _F V _(TO)	I _F = 25 A, T _j = 25 °C T _i = 150 °C		0,8 13		V mΩ
V _F V _(TO) r _T	I _F = 25 A, T _j = 25 °C				
V _F V _(TO) r _T R _{th(j-s)}	$I_F = 25 \text{ A}, T_j = 25 ^{\circ}\text{C}$ $T_j = 150 ^{\circ}\text{C}$ $T_j = 150 ^{\circ}\text{C}$ per diode		13		mΩ
V _F V _(TO) r _T R _{th(j-s)} Temperati	$I_F = 25 \text{ A}, T_j = 25 \text{ °C}$ $T_j = 150 \text{ °C}$ $T_j = 150 \text{ °C}$ per diode		13 2		mΩ
V _F V _(TO) r _T R _{th(j-s)} Temperati R _{ts}	$I_{F} = 25 \text{ A}, T_{j} = 25 \text{ °C}$ $T_{j} = 150 \text{ °C}$ $T_{j} = 150 \text{ °C}$ per diode $T \text{ sensor}$ $\%, T_{r} = () \text{ °C}$		13		mΩ K/W
V _F V _(TO) r _T R _{th(j-s)} Temperati	$I_{F} = 25 \text{ A}, T_{j} = 25 \text{ °C}$ $T_{j} = 150 \text{ °C}$ $T_{j} = 150 \text{ °C}$ per diode $T \text{ sensor}$ $\%, T_{r} = () \text{ °C}$	 	13 2		mΩ K/W



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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